

ABSTRACT

Spherical crystalline silica particles suitable for filler applications for semiconductor sealants having an excellent dielectric characteristics in the millimeter wave band, that is, spherical crystalline silica particles with a high crystallinity and with a large amount of moisture discharged when heated to 800°C or more according to a temperature programmed desorption gas analyzer, and a method of production of the same and a resin composite composition and resin composite containing those spherical crystalline silica particles are provided.

Spherical crystalline silica particles having a roundness of 0.80 or more, containing crystalline silica in 50.0% or more of the whole, and having an amount of moisture discharged when heating from 800°C to 1000°C by a temperature programmed desorption gas analyzer of $4.5 \mu\text{g}/\text{m}^2$ or more and a method of production of the same and a resin composite composition and resin composite containing those spherical crystalline silica particles.

[No figure]